



Please note that Cypress is an Infineon Technologies Company.

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

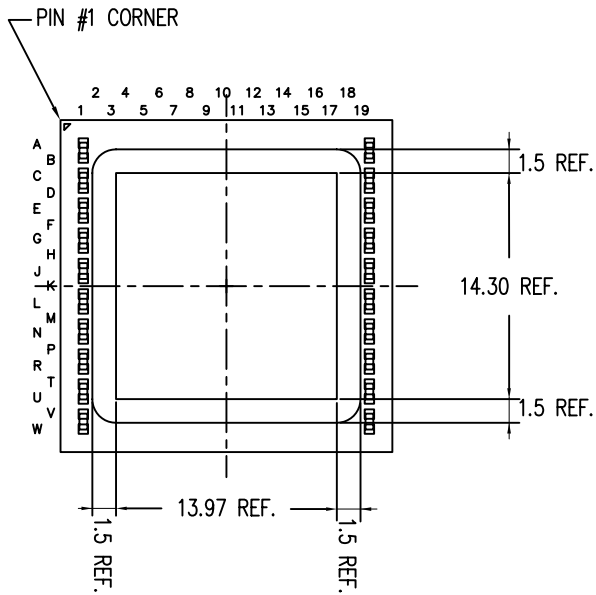
Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

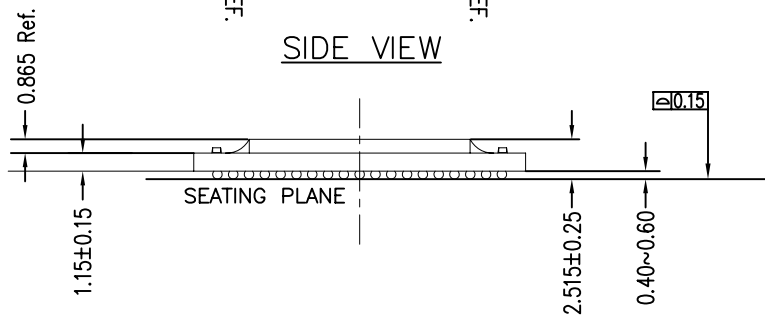
Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

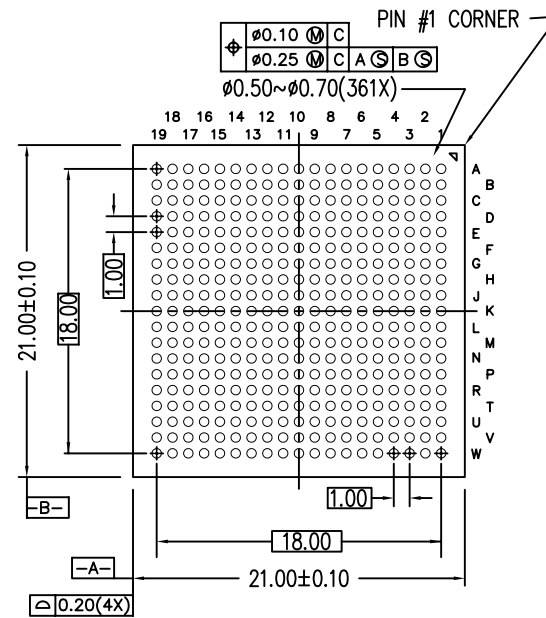
TOP VIEW



SIDE VIEW



BOTTOM VIEW



NOTES:

ALL DIMENSIONS ARE IN MILLIMETERS
 SOLDER BALL DIAMETER: 0.63
 SOLDER PAD TYPE: SOLDER MASK DEFINED (SMD)
 PACKAGE CODE: FROAA



TITLE PACKAGE OUTLINE, 361L FCBGA 21X21X2.515MM
 FROAA

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MATERIAL	N/A	DRAWN BY	CS	DATE	7/23/12	SIZE	A	PART NO.	FROAA	DWG NO.	001-70319	REV	*D
FINISH	N/A	APPROVED BY	QAD	DATE	08/04/14	SCALED TO FIT					SHEET 1 of 2		

REV	ECN	ORIGIN OF CHANGE	DESCRIPTION OF CHANGE
**	3291448	CS	NEW RELEASE
*A	3442794	CS	UPDATED TOP VIEW, SIDE VIEW, PKG WEIGHT, ADDED BALL DIA, AND CHANGED PACKAGE CODE TO FROAA.
*B	3691601	CS	REVISED TO MATCH NEW SUBSTRATE DESIGN
*C	4307001	CS	REMOVED FOR ENGINEERING ONLY AND UPDATED DRAWING TEMPLATE
*D	4464649	XANC	UPDATE DHP TEMPLATE. FOR SUNSET REVIEW.



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MATERIAL	N/A	DRAWN BY	CS	DATE	7/23/12
FINISH	N/A	APPROVED BY	BSC	DATE	7/23/12

SIZE	PART NO.	DWG NO	REV
A	FROAA	001-70319	*D
SCALED TO FIT			SHEET 2 of 2